

isc N-Channel MOSFET Transistor

2SK1008

DESCRIPTION

- Drain Current $-I_D=4.5A@ T_C=25^\circ C$
- Drain Source Voltage-
: $V_{DSS}= 500V(\text{Min})$
- Minimum Lot-to-Lot variations for robust device performance and reliable operation

APPLICATIONS

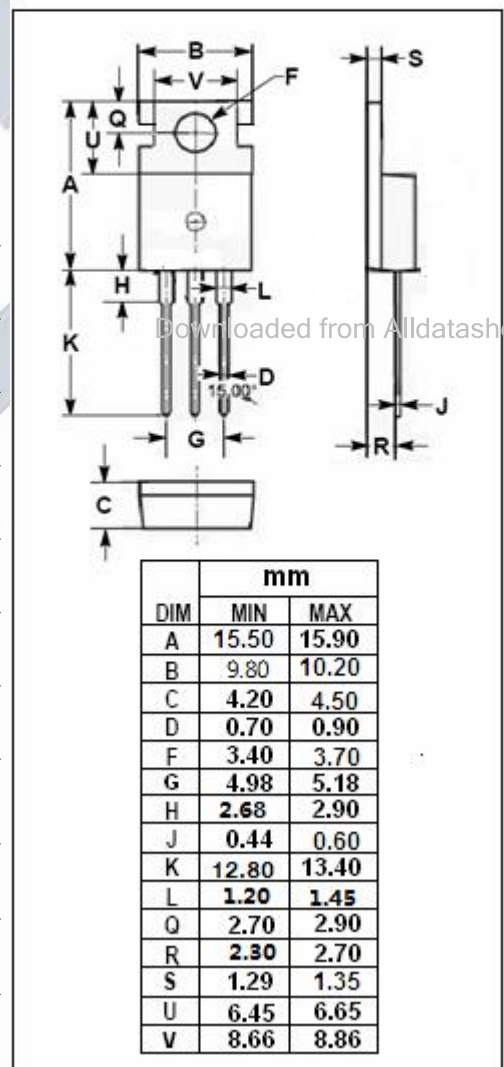
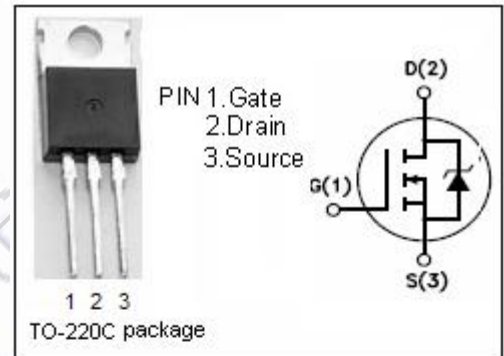
- high voltage, high speed power switching

ABSOLUTE MAXIMUM RATINGS($T_a=25^\circ C$)

SYMBOL	PARAMETER	VALUE	UNIT
V_{DSS}	Drain-Source Voltage ($V_{GS}=0$)	500	V
V_{GS}	Gate-Source Voltage	± 30	V
I_D	Drain Current-continuous@ $T_C=25^\circ C$	4.5	A
P_{tot}	Total Dissipation@ $T_C=25^\circ C$	60	W
T_j	Max. Operating Junction Temperature	150	$^\circ C$
T_{stg}	Storage Temperature Range	-55~150	$^\circ C$

THERMAL CHARACTERISTICS

SYMBOL	PARAMETER	MAX	UNIT
$R_{th\ j-c}$	Thermal Resistance, Junction to Case	2.08	$^\circ C/W$
$R_{th\ j-a}$	Thermal Resistance, Junction to Ambient	75	$^\circ C/W$



isc N-Channel Mosfet Transistor**2SK1008****• ELECTRICAL CHARACTERISTICS (T_c=25°C)**

SYMBOL	PARAMETER	CONDITIONS	MIN	TYP.	MAX	UNIT
V _{(BR)DSS}	Drain-Source Breakdown Voltage	V _{GS} = 0; I _D = 1mA	500			V
V _{GS(th)}	Gate Threshold Voltage	V _{DS} = V _{GS} ; I _D =1mA	2.5	3.5	5.0	V
R _{DS(on)}	Drain-Source On-stage Resistance	V _{GS} =10V; I _D = 2.5A		1.5	2.2	Ω
I _{GSS}	Gate Source Leakage Current	V _{GS} = ±30V; V _{DS} = 0			±100	nA
I _{DSS}	Zero Gate Voltage Drain Current	V _{DS} = 500V; V _{GS} = 0			500	uA
V _{SD}	Forward On-Voltage	I _S =4.5A; V _{GS} =0		1.0	1.5	V
t _r	Rise time	V _{GS} =10V; I _D =10A; R _L =25 Ω		50	80	ns
t _{on}	Turn-on time			60	95	ns
t _f	Fall time			50	80	ns
t _{off}	Turn-off time			130	200	ns